



Kester 952 S

LOW SOLID, NO CLEAN

General Information

Kester 952 S is a halogen-free, non rosin organic flux designed for wave soldering conventional and surface mount circuit board assemblies. The extremely low solid content (2%) and nature of activator system results in practically NO RESIDUES left on the assembly after soldering. Boards are dry and cosmetically clean as they exit the wave solder machine. There are no residues to interfere with electrical testing and the expense of cleaning is eliminated.

Kester 952 S is exhibiting improved soldering performance to minimize soldering bridges (shorts) and excessive solder defects. This non-corrosive and non conductive flux meets the strictest requirements of Bellcore TR-TSY-000078 specification. This flux is suitable for automotive, computer, telecommunications and other applications where reliability considerations are critical. The surface insulation resistance on soldered boards is higher than that provided by typical organic water-soluble fluxes.

Performance Characteristics

- Eliminates the expense of cleaning
- Improved soldering performance
- Non-corrosive and halogen-free
- No surface insulation resistance degradation
- Conforms to Bellcore TR-TSY-000078 specification

Application

The flux can be only applied by spraying equipment. The optimum preheat temperature for many circuit board assemblies is 93-110 °C as measured on the top side of the circuit board. The combination of board design, length of contact time with molten solder, solder wave shape, speed or solder flow and preheating time can all affect the optimum preheat temperature required and the necessary parameters to optimize soldering performance.

Physical Properties

- Specific gravity (23°C) 0,803 g/cm³
DIN 51757
- Solid content 2%
IPC-TM-650 2.3.34
- Acid number 15-16 mg KOH/g
DIN 53402
- Flash point 12 °C
DIN 51755
- Autoignition temperature 634 °C
DIN 51794
- Copper mirror pass
IPC-TM-650 2.6.15

- Thinner 108 S

Surface Insulation Resistance

Kester 952 S will meet the surface insulation resistance requirements of Bellcore TR-TSY-000078 for telecommunications electronics.

Environment	40°C, 93% relative humidity
Bias voltage	45-50 volts DC
Comb pattern board	25 mil lines, 50 mil spaces

Insulation resistance (11 days)

Pattern up	$3 \times 10^{12} \Omega$
pattern down	$2 \times 10^{12} \Omega$
unsoldered control(IR _A)	$1 \times 10^{12} \Omega$
IR min	$9 \times 10^{10} \Omega$
Requirements:IR min =	$(10^{11} \times IR_A) : (10^{11} + IR_A)$